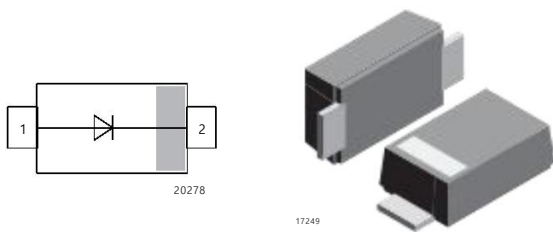
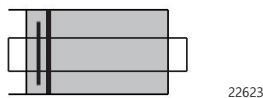


Surface Mount ESD Protection Diodes



MARKING (example only)



Bar = cathode marking
 YY = type code (see table below)
 XX = date code

FEATURES

- 200 W peak pulse power capability with a 10/1000 μ s waveform, repetition rate (duty cycle): 0.01 %
- Low-profile package
- Wave and reflow solderable
- ESD-protection acc. IEC 61000-4-2 \pm 30 kV contact discharge \pm 30 kV air discharge
- ESD capability according to AEC-Q101: human body model: class H3B: > 8 kV
- Low incremental surge resistance, excellent clamping capability
- "Low-Noise" technology - very fast response time
- AEC-Q101 qualified available
- Material categorization: for definitions of compliance

AUTOMOTIVE
 GRADE
 Available



ROHS
 COMPLIANT
 HALOGEN
 FREE
 Available

ORDERING INFORMATION							
PART NUMBER (EXAMPLE)	ENVIRONMENTAL AND QUALITY CODE				PACKAGING CODE		ORDERING CODE (EXAMPLE)
	AEC-Q101 QUALIFIED	RoHS-COMPLIANT + LEAD (Pb)-FREE TERMINATIONS		TIN PLATED	3K PER 7" REEL (8 mm TAPE), 30K/BOX = MOQ	50K PER 13" REEL (8 mm TAPE), 50K/BOX = MOQ	
		STANDARD	HALOGEN-FREE				
SMF5V0A-		E		3	-08		SMF5V0A-E3-08
SMF5V0A-			M	3	-08		SMF5V0A-M3-08
SMF5V0A-	H	E		3	-08		SMF5V0A-HE3-08
SMF5V0A-	H		M	3	-08		SMF5V0A-HM3-08
SMF5V0A-		E		3		-18	SMF5V0A-E3-18
SMF5V0A-			M	3		-18	SMF5V0A-M3-18
SMF5V0A-	H	E		3		-18	SMF5V0A-HE3-18
SMF5V0A-	H		M	3		-18	SMF5V0A-HM3-18

PACKAGE DATA									
PACKAGE NAME	MOLDING COMPOUND	WEIGHT (mg)	HEIGHT MAX. (mm)	LENGTH MAX. (mm)	WIDTH MAX. (mm)	MOLDING COMPOUND FLAMMABILITY RATING	MOISTURE SENSITIVITY LEVEL	WHISKER TEST ACC. JESD 201	SOLDERING CONDITIONS
SMF (DO-219AB)	Standard	15	1.08	3.9	1.9	UL 94 V-0	MSL level 1 (acc. J-STD-020)	class 2	Peak temperature max. 260 °C
	Halogen-free								

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
Peak pulse current	$t_p = 10/1000\text{ }\mu\text{s}$ waveform	I_{PPM}	see "Electrical Characteristics"	A
Peak pulse power	$t_p = 8/20\text{ }\mu\text{s}$ waveform acc. IEC 61000-4-5	P_{PP}	1000	W
	$t_p = 10/1000\text{ }\mu\text{s}$ waveform		200	W
Peak forward surge current	8.3 ms single half sine-wave	I_{FSM}	50	A
ESD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	V_{ESD}	± 30	kV
	Air discharge acc. IEC 61000-4-2; 10 pulses		± 30	kV
Thermal resistance	Mounted on epoxy glass PCB with 3 mm x 3 mm, Cu pads ($\geq 40\text{ }\mu\text{m}$ thick)	R_{thJA}	180	K/W
Forward clamping voltage	$I_F = 50\text{A}$, $t_p = 400\text{ }\mu\text{s}$	V_F	2.5	V
Junction temperature		T_J	175	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-65 to +175	$^{\circ}\text{C}$
Operating temperature range		T_{op}	-65 to +175	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)										
PART NUMBER	TYPE CODE		REVERSE BREAKDOWN VOLTAGE at I_T , $t_p = 5\text{ ms}$	TEST CURRENT	REVERSE WORKING VOLTAGE	REVERSE CURRENT at V_{RWM}	PEAK PULSE CURRENT $t_p = 10/1000\text{ }\mu\text{s}$	REVERSE CLAMPING VOLTAGE at I_{PPM}	CAPACITANCE at $V_R = 0\text{V}$, $f = 1\text{ MHz}$	PROTECTION PATHS
	STD.	HALOGEN-FREE	$V_{BRMIN.}$ (V)	I_T (mA)	V_{RWM} (V)	I_R (μA)	I_{PPM} (A)	V_C MAX. (V)	C_D TYP. (pF)	$N_{channel}$
SMF5V0A	AE	NE	6.40	10	5	5	21.7	9.2	1120	1
SMF6V0A	AG	NG	6.67	10	6	26	19.4	10.3	1063	1
SMF6V5A	AK	NK	7.22	10	6.5	20	17.9	11.2	938	1
SMF7V0A	AM	NM	7.78	10	7	3	16.7	12	843	1
SMF7V5A	AP	NP	8.33	1	7.5	0.1	15.5	12.9	773	1
SMF8V0A	AR	NR	8.89	1	8	0.1	14.7	13.6	706	1
SMF8V5A	AT	NT	9.44	1	8.5	0.1	13.9	14.4	674	1
SMF9V0A	AV	NV	10	1	9	0.1	13.5	15.4	640	1
SMF10A	AX	NX	11.1	1	10	0.1	11.8	17	562	1
SMF11A	AZ	NZ	12.2	1	11	0.1	11	18.2	509	1
SMF12A	BE	OE	13.3	1	12	0.1	10.1	19.9	483	1
SMF13A	BG	OG	14.4	1	13	0.1	9.3	21.5	423	1
SMF14A	BK	OK	15.6	1	14	0.1	8.6	23.2	392	1
SMF15A	BM	OM	16.7	1	15	0.1	8.2	24.4	367	1
SMF16A	BP	OP	17.8	1	16	0.1	7.7	26	343	1
SMF17A	BR	OR	18.9	1	17	0.1	7.2	27.6	324	1
SMF18A	BT	OT	20	1	18	0.1	6.8	29.2	320	1
SMF20A	BV	OV	22.2	1	20	0.1	6.2	32.4	283	1
SMF22A	BX	OX	24.4	1	22	0.1	5.6	35.5	271	1
SMF24A	BZ	OZ	26.7	1	24	0.1	5.1	38.9	244	1
SMF26A	CE	PE	28.9	1	26	0.1	4.8	42.1	230	1
SMF28A	CG	PG	31.1	1	28	0.1	4.4	45.4	227	1
SMF30A	CK	PK	33.3	1	30	0.1	4.1	48.4	207	1
SMF33A	CM	PM	36.7	1	33	0.1	3.8	53.3	198	1
SMF36A	CP	PP	40	1	36	0.1	3.4	58.1	178	1
SMF40A	CR	PR	44.4	1	40	0.1	3.1	64.5	172	1
SMF43A	CT	PT	47.8	1	43	0.1	2.9	69.4	165	1
SMF45A	CV	PV	50	1	45	0.1	2.8	72.7	162	1
SMF48A	CX	PX	53.3	1	48	0.1	2.6	77.4	161	1
SMF51A	CZ	PZ	56.7	1	51	0.1	2.4	82.4	151	1
SMF54A	CA	PA	60	1	54	0.1	2.25	88	148	1
SMF58A	CC	PC	64.4	1	58	0.1	2.1	95	144	1

TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

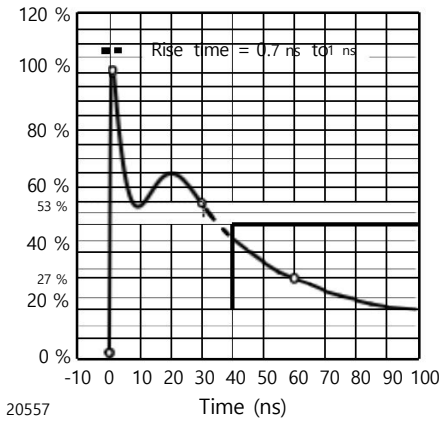


Fig. 1 - ESD Discharge Current Wave Form acc. IEC 61000-4-2 (330 Ω /150pF)

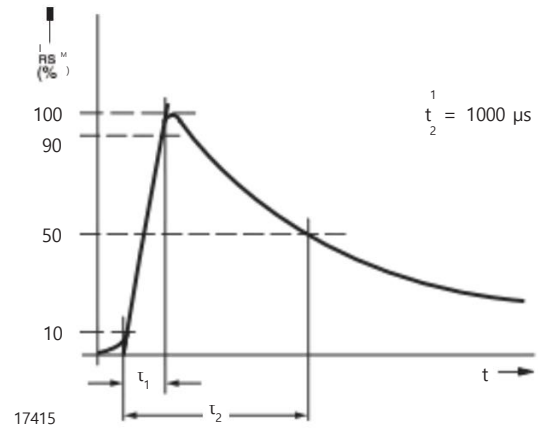


Fig. 4 - Pulse Waveform

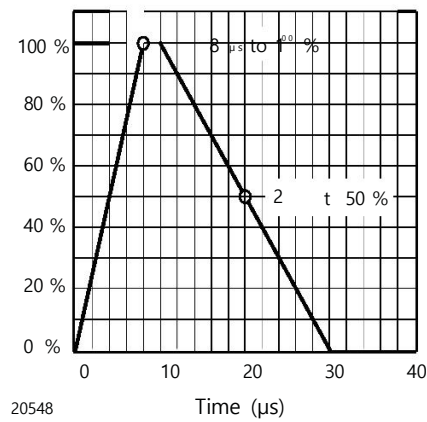


Fig. 2 - 8/20 μs Peak Pulse Current Wave Form acc. IEC 61000-4-5

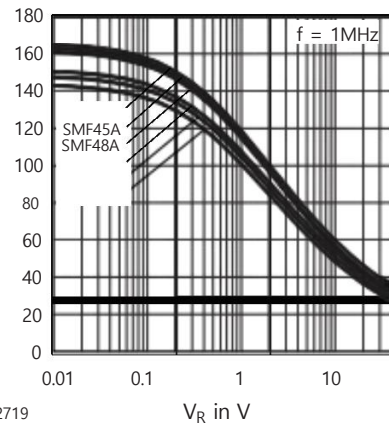


Fig. 5 - Typical Capacitance C_D vs. Reverse Voltage V_R

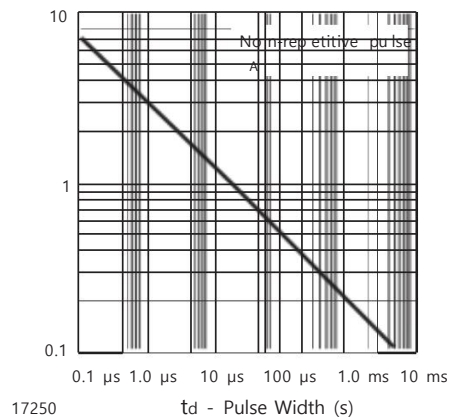


Fig. 3 - Peak Pulse Power Rating

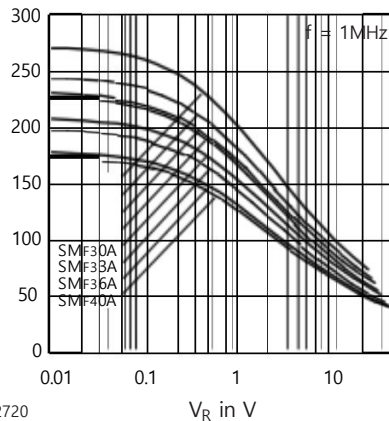


Fig. 6 - Typical Capacitance C_D vs. Reverse Voltage V_R

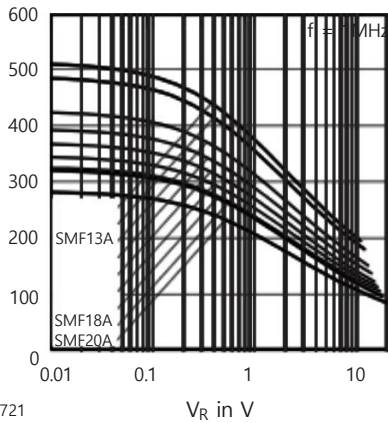


Fig. 7 - Typical Capacitance CD vs. Reverse Voltage VR

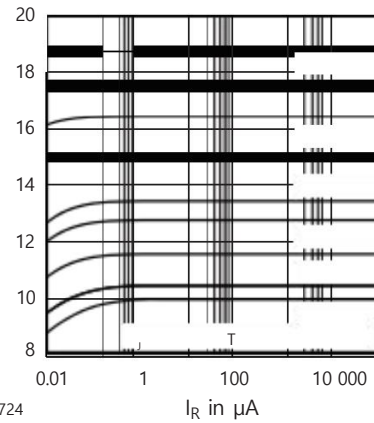


Fig. 10 - Typical Reverse Voltage VR vs. Reverse Current IR

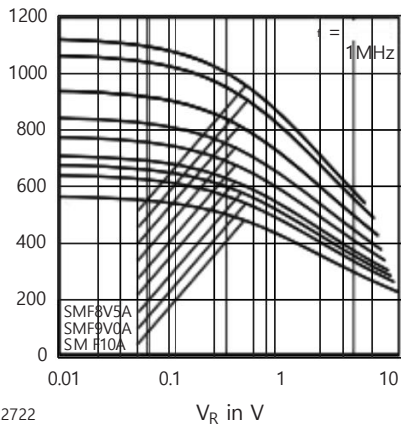


Fig. 8 - Typical Capacitance CD vs. Reverse Voltage VR

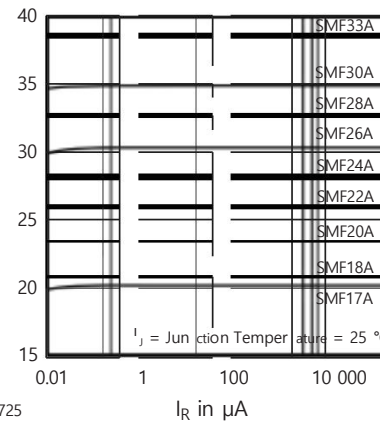


Fig. 11 - Typical Reverse Voltage VR vs. Reverse Current IR

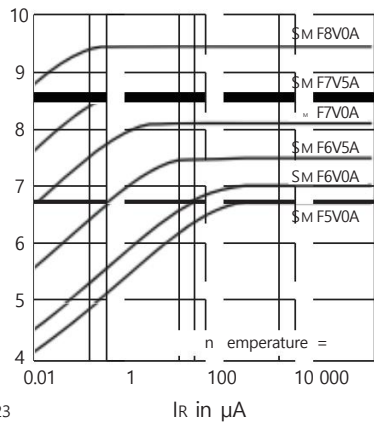


Fig. 9 - Typical Reverse Voltage VR vs. Reverse Current IR

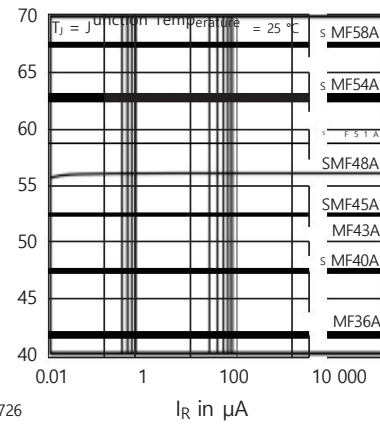
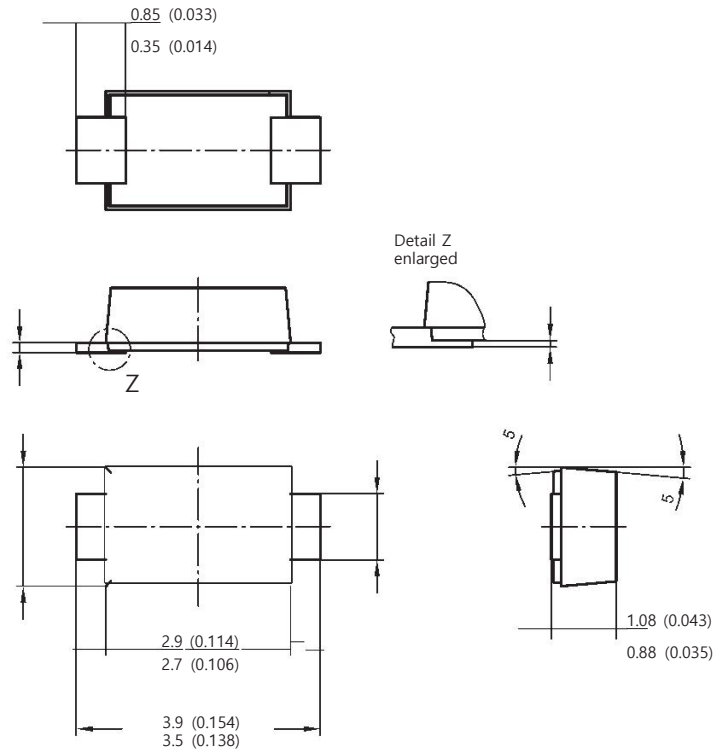
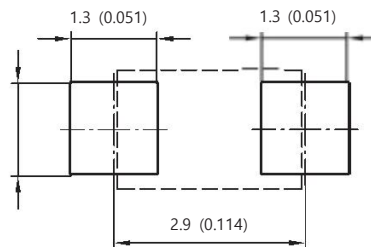


Fig. 12 - Typical Reverse Voltage VR vs. Reverse Current IR

PACKAGE DIMENSIONS in millimeters (inches): SMF

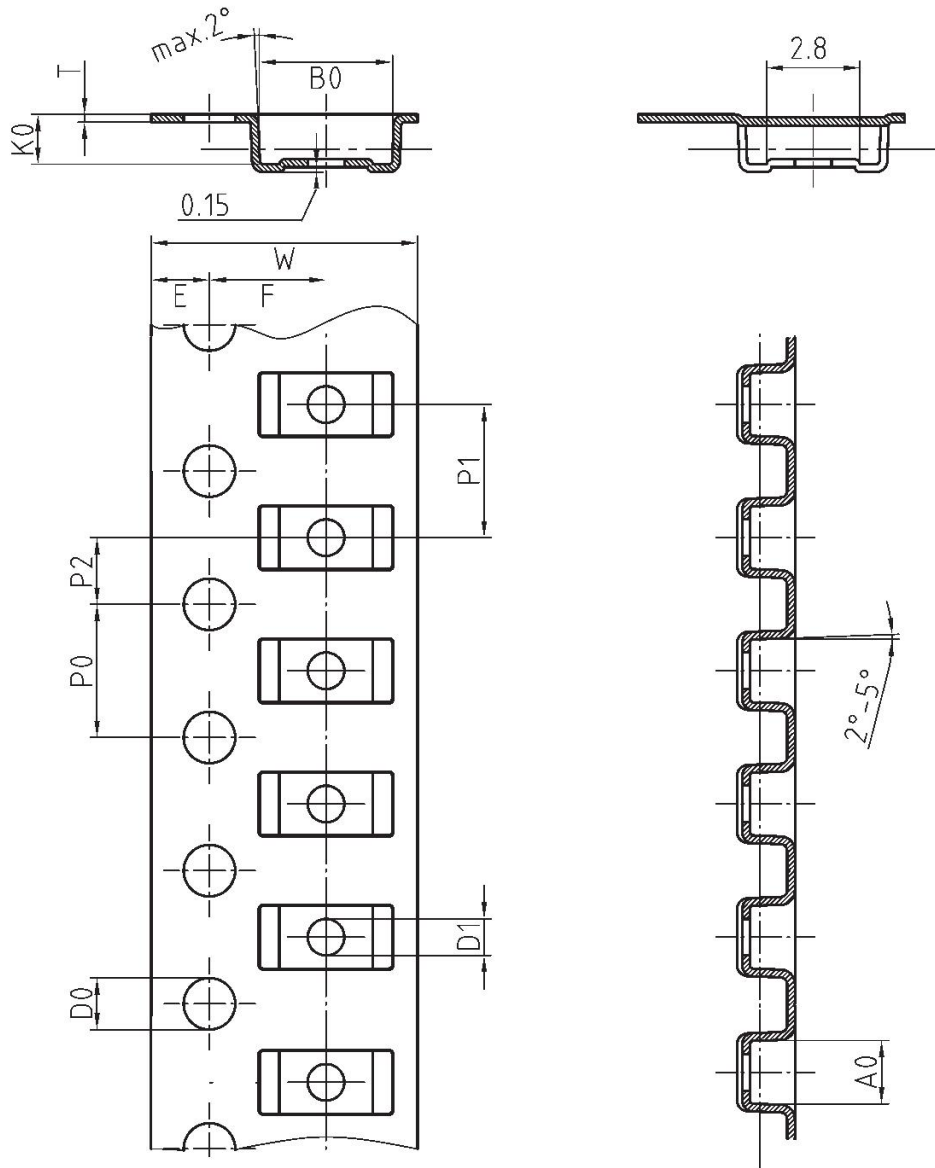


Foot print recommendation:



Created - Date: 15. February 2005
 Rev. 3 - Date: 13. March 2007
 Document no.:S8-V-3915.01-001 (4)
 17247

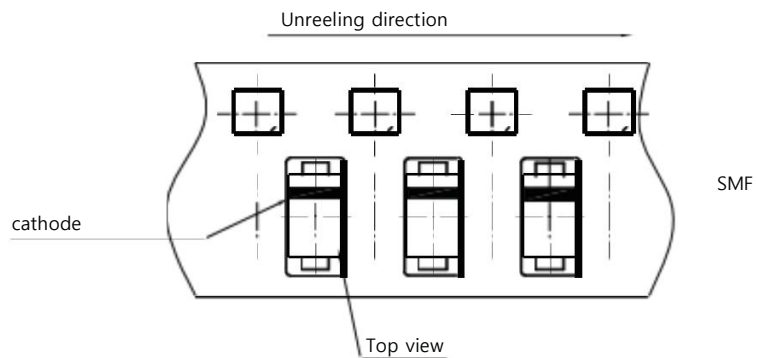
BLISTERTAPE DIMENSIONS in millimeters (inches)



Mat:	A0	B0	K0	W	T	P0	P2	P1	D0	D1	E	F
PS	1.9	4.0	1.5	8.0	0.235	4.0	2.0	4.0	1.5	1	1.75	3.5

Document-No.: S8-V-3717.02-001 (3)
18513

ORIENTATION IN CARRIER TAPE - SMF



Document no.: S8-V-3717.02-003 (4)
Created - Date: 09. Feb. 2010
22670